

Multilayer Ceramic Chip Capacitors

C5750X5R1H106M230KA



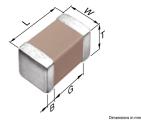






TDK item description C5750X5R1H106MT****

Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C5750 [EIA 2220]	
Status	Production	



	Size
Length(L)	5.70mm ±0.40mm
Width(W)	5.00mm ±0.40mm
Thickness(T)	2.30mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	
Recommended Land Pattern (PA)	4.10mm to 4.80mm
Recommended Land Pattern (PB)	1.20mm to 1.40mm
Recommended Land Pattern (PC)	4.00mm to 5.00mm

Electrical Characteristics		
Capacitance	10μF ±20%	
Rated Voltage	50VDC	
Temperature Characteristic	X5R(±15%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	50ΜΩ	

Other	
Soldering Method	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	500pcs

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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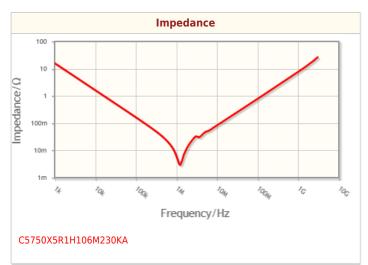


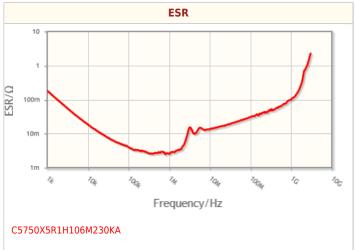


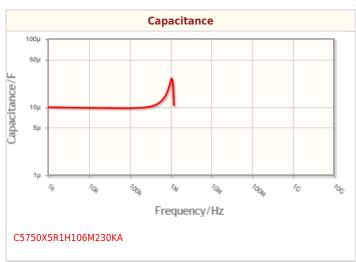


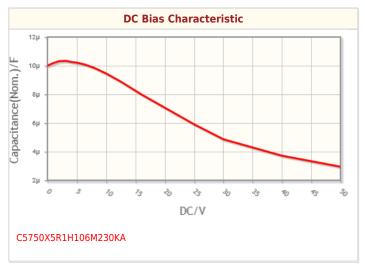


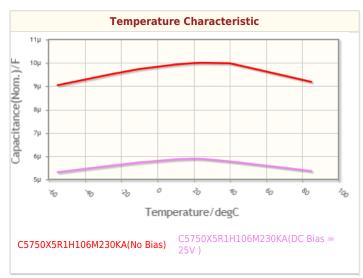
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

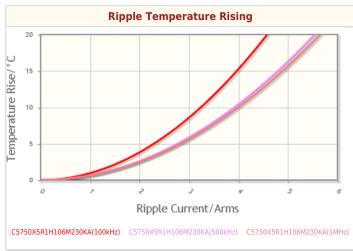












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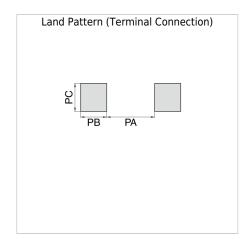








Associated Images



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